

PATENT ABSTRACTS OF JAPAN

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(54) RESIN SEALING METHOD OF SEMICONDUCTOR CHIP

(57)Abstract:

PURPOSE: To improve moisture resisting reliability, by pretreating a semiconductor chip with chloroalkylsilane expressed by R₂SiCl₂ or/and RSiCl₃, and thereafter performing resin sealing.

CONSTITUTION: Chloroalkylsilane expressed by R₂SiCl₂ or/and RSiCl₃ including an alkyl group of C₃WC₂₀ or a phenyl group R is dissolved in toluene or the like and applied on the surface of a chip. After drying, the surface is washed with toluene or the like, and the excessive silane treating agent is washed away. After drying, epoxy resin sealing is performed. In this constitution, adhesion between the chip and the resin is improved, and the moisture resisting reliability is improved.

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